

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/30/2022

Details for "ISO7242ADWR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
ISO7242ADWR	NIPDAU	Level-2-260C-1 YEAR	TI TAIWAN A/T	DW 16	7.52x10.28x2.35	634.2

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.00002	0.000249	2	0	0
Other Nonferrous Metals and Alloys	Beryllium	7440-41-7	0.00001	0.000125	1	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.00002	0.000249	2	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.00006	0.000748	7	0.000001	0
Precious Metals	Gold	7440-57-5	0.801956	99.997506	999975	0.126452	1265
Precious Metals	Silver	7440-22-4	0.000009	0.001122	11	0.000001	0
Sub-Total			0.801976	100	1000000	0.126456	1265
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.564333	75	750000	0.088984	890
Thermoplastics	Epoxy	85954-11-6	0.188111	25	250000	0.029661	297
Sub-Total			0.752444	100	1000000	0.118645	1186
Die Attach Adhesive 2							
Precious Metals	Silver	7440-22-4	0.564333	75	750000	0.088984	890
Thermoplastics	Epoxy	85954-11-6	0.188111	25	250000	0.029661	297
Sub-Total			0.752444	100	1000000	0.118645	1186
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	272.06698	97.585	975850	42.899514	428995
Copper and Its Alloys	Iron	7439-89-6	6.4124	2.3	23000	1.011107	10111
Copper and Its Alloys	Phosphorus	7723-14-0	0.04182	0.015	150	0.006594	66
Zinc and Its Alloys	Zinc	7440-66-6	0.2788	0.1	1000	0.043961	440
Sub-Total			278.8	100	1000000	43.961177	439612
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.279364	95.12	951200	0.20173	2017
Precious Metals	Gold	7440-57-5	0.010491	0.78	7800	0.001654	17
Precious Metals	Palladium	7440-05-3	0.055145	4.1	41000	0.008695	87
Sub-Total			1.345	100	1000000	0.21208	2121
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	297.771157	86	860000	46.952548	469525
Other Plastics and Rubber	Carbon Black	1333-86-4	1.038737	0.3	3000	0.163788	1638
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	1.90435	0.55	5500	0.300278	3003
Thermoplastics	Epoxy	85954-11-6	45.531287	13.15	131500	7.179372	71794
Sub-Total			346.245531	100	1000000	54.595986	545960
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.749274	100	1000000	0.433505	4335
Sub-Total			2.749274	100	1000000	0.433505	4335
Semiconductor Device 2							
Ceramics / Glass	Doped Silicon	7440-21-3	2.749274	100	1000000	0.433505	4335
Sub-Total			2.749274	100	1000000	0.433505	4335
Total			634.195943			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, see Product Content Methodology.

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 05/30/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet I5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.